

L Number	Hits	Search Text	DB	Time stamp
1	6	("5191708" "5974662" "5804983").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 19:44
2	448	lippmann.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 19:45
3	28	lippmann.in. and chintyan.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 19:45
-	2	"20020151200"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 16:48
-	85	esd same spark same gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 16:50
-	66	esd same spark same gap same discharge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 16:51
-	4	esd same spark same gap same discharge same structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 11:30
-	2	4179178.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 13:16
-	1	6493198.URPN.	USPAT	2004/03/18 13:14
-	77	esd same spark near gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 13:16
-	15	(esd same spark near gap) same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:02
-	5907	(multilayer multy-layer) near substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:03
-	5907	(multilayer) near substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:04
-	603	(multilayer) near substrate same thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:04

-	0	(multilayer) near substrate same thickness same esd	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:05
-	2	(multilayer) near substrate same thickness same discharge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:06
-	38	(multilayer) near substrate same thickness same (micrometer micron)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:06
-	16	(multilayer) near substrate same thickness same (micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:09
-	4	(multilayer) near substrate same layer near thickness same (micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:45
-	4	(multilayer) near substrate same layer near thickness same (micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:45
-	28452	esd same gap thickness same (micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:46
-	0	esd same gap same thickness same (micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:46
-	0	esd same gap same (micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:47
-	6	esd same spark adj gap same size	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 13:05
-	1	esd same spark adj gap same substrate same layer same trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 13:07
-	4	esd same spark adj gap same substrate same trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:24
-	23	("3852563" "4429321" "4458256" "4513298" "4535343" "4596994" "4695853" "4716421" "4719477" "4803500" "4812859" "4862197" "4872027" "4899180" "4930915" "4961103" "4963897" "5103246" "5206668" "5235351" "5278584" "5315472" "5363134") .PN.	USPAT	2004/03/19 13:12

-	15	esd same spark adj gap same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:35
-	5	esd same spark adj gap same conductive near element	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:56
-	1050	substrate same trace same laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:56
-	19	substrate same trace same laser near (cut cutting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 19:39